Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("6245596").PN.	US-PGPUB; USPAT	OR	OFF	2005/09/15 07:44
L2	1	("6136668").PN.	US-PGPUB; USPAT	OR	OFF	2005/09/15 07:45
L3	5	sigulat$3 and (substrate or wafer) and (etch or etching)	US-PGPUB; USPAT	OR	ON	2005/09/15 08:01
L4	0	sigulat$3 and (substrate or wafer) and (reducing or thinning)	US-PGPUB; USPAT	OR	ON	2005/09/15 08:02
L5	0	sigulat$3 and (substrate or wafer) and (thickness with thinning)	US-PGPUB; USPAT	OR	ON	2005/09/15 08:02
L8	0	sigulat$3 and (substrate or wafer) and (thickness with thinning)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 08:03
L9	0	sigulat$3 and (substrate or wafer) and (thickness with reducing)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 08:03
L10	0	sigulat$3 and (substrate or wafer) and (thickness with reducing)	US-PGPUB; USPAT	OR	ON	2005/09/15 08:05
L12	0	sigulat$3 and (substrate or wafer) and (backgrind$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 08:05
L13	82	separating and (substrate or wafer) and (backgrind$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 08:06
L14	52	13 and @ad<"20040310"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 08:06